

ABSTRACT OF THE DISCLOSURE

ALKALINE POST-CHEMICAL MECHANICAL PLANARIZATION CLEANING
COMPOSITIONS

A post-CMP cleaning composition and method comprising same are disclosed herein. In one aspect, there is provided a composition comprising: water, an organic
5 base, and a plurality of chelating agents comprised of a poly-amino carboxylic acid and a hydroxyl carboxylic acid wherein the pH of the composition ranges from 9.5 to 11.5.

Figure 1